

AJV:kaa 03/09/05 362077
PATENT

Attorney Reference Number 6047-67518-01
Application Number 10/731,995

Claims

1-39. (canceled)

40. (previously amended) A mold for molding a package for at least one die bonded to a substrate, the mold comprising a first mold portion that defines a package cover for encapsulating the at least one die and a portion of a surface of the substrate to which the die is bonded, and a second mold portion that defines a rib having a thickness at least as great as a solder bump thickness and that projects outwardly from a surface of the substrate opposite the surface of the substrate to which the at least one die is bonded.

41. (original) The mold of claim 40, wherein the first mold portion and the second mold portion define package covers and ribs for a plurality of die bonded to the substrate.

42. (currently amended) The mold of claim ~~42~~ 40, wherein the first mold portion is configured to define the package cover to encapsulate at least a portion of the surface of the substrate opposite the surface of the substrate to which the at least one die is bonded.

43. (previously presented) The mold of claim 42, wherein the first mold portion is configured to contact the second mold portion.

44. (previously presented) The mold of claim 42, wherein the first mold portion is configured to define the cover to encapsulate at least a portion of a substrate edge.

45. (previously presented) The mold of claim 42, wherein the second mold portion is configured to encapsulate at least a portion of a substrate edge.

46. (previously presented) The mold of claim 40, wherein the first mold portion is configured to contact the second mold portion.

47-48. (canceled)

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49. (previously presented) A mold for molding a package for at least one die bonded to a substrate, the mold comprising a first mold portion that defines a package cover for encapsulating the at least one die and at least a perimeter portion of a surface to which the die is bonded, and a second mold portion that defines a rib that projects outwardly from a surface of the substrate opposite the surface of the substrate to which the at least one die is bonded, wherein the first mold portion and the second mold portion define package covers and ribs for a plurality of die bonded to one or more substrates, wherein the rib defined by the second mold portion has a thickness at least as great as a solder ball thickness.

50-55. (canceled)

56. (new) A mold for molding a package for at least one die bonded to a substrate, the mold comprising a first mold portion that defines a package cover for encapsulating the at least one die and a portion of a surface of the substrate to which the die is bonded, and a second mold portion that defines a rib having a thickness at least as great as a solder bump thickness and that projects outwardly from a surface of the substrate opposite the surface of the substrate to which the at least one die is bonded, wherein the first mold portion is configured to define the package cover to encapsulate at least a portion of the surface of the substrate opposite the surface of the substrate to which the at least one die is bonded.

57. (new) The mold of claim 56, wherein the first mold portion is configured to contact the second mold portion.

58. (new) The mold of claim 56, wherein the first mold portion is configured to define the cover to encapsulate at least a portion of a substrate edge.

59. (new) The mold of claim 56, wherein the second mold portion is configured to encapsulate at least a portion of a substrate edge.